

Electronic Patent Application Fee Transmittal

Application Number:	10696006			
Filing Date:	29-Oct-2003			
Title of Invention:	STRUCTURE FOR REDUCING LEAKAGE CURRENTS AND HIGH CONTACT RESISTANCE FOR EMBEDDED MEMORY AND METHOD FOR MAKING SAME			
First Named Inventor/Applicant Name:	Kuo-Chi Tu			
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Attorney Docket Number:	TS02-1033			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
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Total in USD (\$)				1740